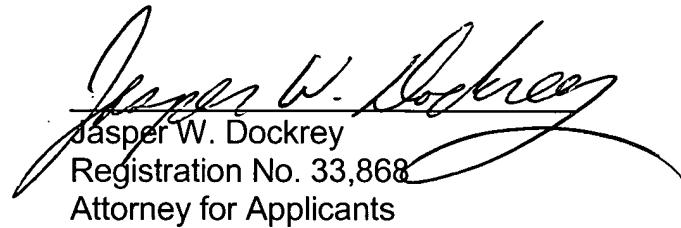


## **REMARKS**

The applicants respectfully request entry of the amendment prior to commencing examination of the application.

Respectfully submitted,



Jasper W. Dockrey  
Registration No. 33,868  
Attorney for Applicants

BRINKS HOFER GILSON & LIONE  
P.O. BOX 10395  
CHICAGO, ILLINOIS 60610  
(312) 321-4200

## Amended Abstract

The invention concerns a method of making a complex microelectronic structure by assembling two substrates (5, 6; 11,13) through two respective linking surfaces, the structure being designed to be dissociated at a separation zone. The invention is characterized in that it consists, prior to ~~assembling~~ assembly, in producing a state difference of state of ~~in the~~ tangential stresses between the two surfaces to be assembled, said the state difference being selected so as to obtain produce in the assembled structure a predetermined stress state of ~~stresses~~ at the time of dissociation.